



Product data sheet

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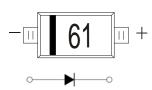






SOD-523

MARKING:61



BAS516 FAST SWITCHING DIODE

FEATURES

- Small Package
- Low Reverse Current
- Fast Switching Speed
- Surface Mount Package Ideally Suited for Automatic Insertion

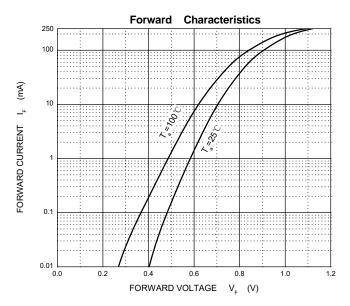
Symbol	Parameter	Value	Unit	
V _{RM}	Non-Repetitive Peak Reverse Voltage	100	V	
V _{RRM}	Peak Repetitive Reverse Voltage 75		V	
V _{RWM}	Working Peak Reverse Voltage	15	v	
V _{R(RMS)}	RMS Reverse Voltage	53	V	
lo	Average Rectified Output Current	250	mA	
I _{FSM}	I _{FSM} Non-repetitive Peak Forward Surge Current @t=8.3ms		А	
PD	Power Dissipation	150	mW	
R _{ØJA}	Thermal Resistance from Junction to Ambient	833	°C/W	
Tj	Junction Temperature	150	°C	
T _{stg}	Storage Temperature	-55~+150	°C	

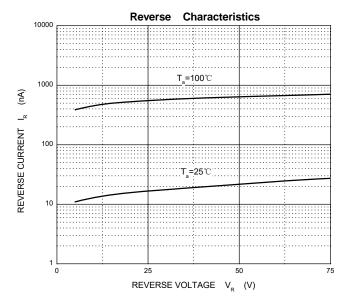
ELECTRICAL CHARACTERISTICS(T_a=25[°]C unless otherwise specified)

Parameter	Symbol	Test conditions	Min	Тур	Max	Unit
Reverse voltage	V _(BR)	I _R =100μA	75			V
Reverse current	I _R	V _R =25V			30	nA
Reverse current		V _R =75V			1	μ Α
	V _F	I _F =1mA			0.715	V
		I _F =10mA			0.855	V
Forward voltage		I _F =50mA			1	V
		I _F =150mA			1.25	V
Total capacitance	C _{tot}	V _R =0V,f=1MHz			1	pF
Reverse recovery time	t _{rr}	I _F = I _R =10mA, I _{rr} =0.1*I _R ,R _L =100 Ω			4	ns



Typical Characteristics





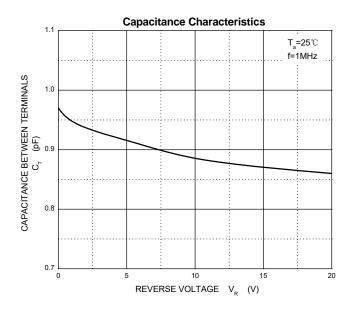
BAS516

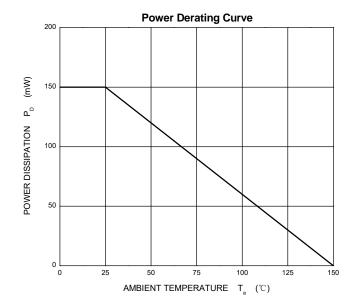
Semiconductor

HF

RoHS

Compiance

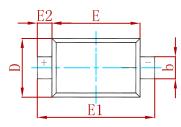


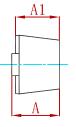


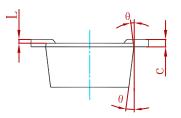




PACKAGE MECHANICAL DATA

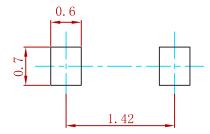






Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.510	0.770	0.020	0.031
A1	0.500	0.700	0.020	0.028
b	0.250	0.350	0.010	0.014
С	0.080	0.150	0.003	0.006
D	0.750	0.850	0.030	0.033
E	1.100	1.300	0.043	0.051
E1	1.500	1.700	0.059	0.067
E2	0.200 REF		0.008 REF	
L	0.010	0.070	0.001	0.003
θ	7° REF		7° F	REF

Suggested Pad Layout



Note: 1.Controlling dimension:in millimeters. 2.General tolerance:±0.05mm.

3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
BAS516	SOD-523	3000





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